Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	432144	epoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L2	1947025	resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L3	4386654	back backside bottom underneath underbody undersurface underside	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L4	721	L3 with (L1 L2) same selectiv$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:49
L5	53876	scrib$4 dicing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:46
L6	81138	L3 with (L1 L2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L7	31377	scrib$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L8	32571	dicing singulat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L9	327	L6 and L5 and L7 and L8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:43
L10	11289	scrib$4 near2 (lines mark$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:47

L11	11429	scrib$4 near2 (lines mark$4 guide feature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:48
L12	11005	scrib$4 near (lines mark$4 guide feature channel trench groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:48
L13	13	L3 with (L1 L2 (heat thermal) near2 (layer spread)) with 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:57
L14	51	L3 same (L1 L2 (heat thermal) near2 (layer spread)) same 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:57
L15	36	L3 with (L1 L2 (heat thermal) near2 (layer spread)) same 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:59
L16	23	15 not 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 15:59
L17	17	16 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 16:03
L18	13	(14 not 15) and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 16:08
L19	241	12 near2 expos$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 16:07
L20	209	19 and (@ad < "20021122")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:23

L21	1189	dicing adj tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:23
L22	158067	(thermal$4 heat$4) adj (conduct$4 constant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:24
L23	934008	silicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:25
L24	1	21 near2 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:26
L25	2	21 with 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:25
L26	419	tape near2 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:27
L27	1199	(silicon si) near2 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:27
L28	13	26 and 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:27
L29	3540202	ic integrated adj circuit chip die dice wafer substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:32
L30	30164	ceramic near2 powder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:33

L31	30164	ceramic near2 powder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:33
L32	6	29 with 3 with metal with 31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 17:37
L33	2873	((438/113) or (438/114) or (438/126) or (438/127)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/30 18:33